

## MMBTH34

## **NPN General Purpose Amplifier**

- This device is designed for common-emitter low noise amplifier and mixer applications with collector currents in the 100mA to 20mA range to 300MHz, and low frequency drift common-base VHF oscillator applications with high output levels for driving FET mixers.
- Sourced from process 47.
- See MPSH11 for characteristics.



1. Base 2. Emitter 3. Collector

## Absolute Maximum Ratings T<sub>C</sub>=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>CEO</sub>	Collector-Emitter Voltage	40	V
V <sub>CBO</sub>	Collector-Base Voltage	40	V
V <sub>EBO</sub>	Emitter-Base Voltage	4.0	V
I <sub>C</sub>	Collector current - Continuous	50	mA
T <sub>J</sub> , T <sub>stq</sub>	Junction and Storage Temperature	-55 ~ +150	°C

### Electrical Characteristics T<sub>C</sub>=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
Off Characte	Off Characteristics					
V <sub>(BR)CEO</sub>	Collector-Emitter Sustaining Voltage *	$I_C = 1.0 \text{mA}, I_B = 0$	30			V
V <sub>(BR)CBO</sub>	Collector-Base Breakdown Voltage	$I_C = 100 \mu A, I_E = 0$	40			
V <sub>(BR)EBO</sub>	Emitter-Base Breakdown Voltage	$I_E = 10\mu A, I_C = 0$	4.0			VV
I <sub>CBO</sub>	Collector Cutoff Current	$V_{CB} = 30V, I_{E} = 0$			50	nA
On Characteristics						
h <sub>FE</sub>	DC Current Gain	$I_C = 20$ mA, $V_{CE} = 2$ V	15			
Small Signal Characteristics						
f <sub>T</sub>	Current Gain Bandwidth Product	I <sub>C</sub> = 15mA, V <sub>CE</sub> = 10V, f = 100MHz	500			MHz

<sup>\*</sup> Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2.0%

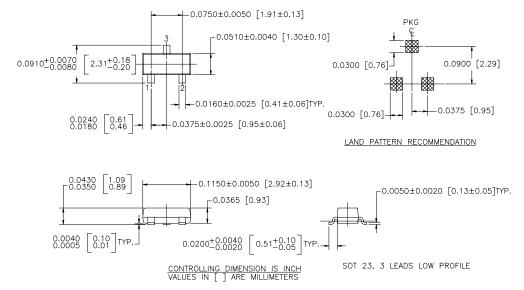
## Thermal Characteristics $T_A=25$ °C unless otherwise noted

Symbol	Parameter	Max.	Units
P <sub>D</sub>	Total Device Dissipation	225	mW
	Derate above 25°C	1.8	mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	556	°C/W

<sup>\*</sup> Device mounted on FR-4 PCB 1.6"  $\times$  1.6"  $\times$  0.06"

# **Package Dimensions**

## **SOT-23**



NOTE: UNLESS OTHERWISE SPECIFIED

- 1. STANDARD LEAD FINISH 150 MICROINCHES / 3.81 MICROMETERS MINIMUM TIN / LEAD (SOLDER) ON ALLOY 42
- 2. REFERENCE JEDEC REGISTRATION TO-236, VARIATION AB, ISSUE G, DATED JUL 1993

Dimensions in Millimeters

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EnSigna™	I <sup>2</sup> C <sup>TM</sup>	$OCX^{TM}$	RapidConfigure™	UHC™
Across the board. Around the world.™		OCXPro™	RapidConnect™	UltraFET <sup>®</sup>
The Power Franchise™		OPTOLOGIC <sup>®</sup>	SILENT SWITCHER®	VCX™
Programmable Ad	ctive Droop™	OPTOPLANAR™	SMART START™	

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